

| Ref # | Hits    | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|---------|---|---|------------------|---------|------------------|
| L4    | 16      | 3 and (silver protect\$4 diffus\$4) and ((protect\$4 or barrier) (Ti or TiN or W))                          | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH             | ON      | 2005/07/20 14:32 |
| L5    | 1540465 | semiconductor   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH             | ON      | 2005/07/20 14:33 |
| L6    | 16      | 5 and (silver protect\$4 diffus\$4) and ((protect\$4 or barrier) (Ti or TiN or W))                          | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH             | ON      | 2005/07/20 14:33 |
| L7    | 1540465 | semiconductor   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH             | ON      | 2005/07/20 14:33 |
| L8    | 16      | 7 and (silver protect\$4 diffus\$4) and ((protect\$4 or barrier) (Ti or TiN or W))                          | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH             | ON      | 2005/07/20 14:33 |
| S39   | 1829    | 257/768,763,770.ccls.   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/07/20 12:45 |
| S40   | 1       | S39 and ((silver or copper or aluminum or gold) same interface same protection same dielectric)             | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/03/23 10:01 |
| S41   | 13      | interconnect\$4 and ((silver or copper or aluminum or gold) same interface same protection same dielectric) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/03/23 10:36 |
| S42   | 7       | S41 and sputter\$4  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/03/23 10:02 |

|     |        |  |   |    |    |                  |
|-----|--------|--|---|----|----|------------------|
| S43 | 6986   | interconnect\$4 and ((silver or copper or aluminum or gold) with sputter\$4)                     | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:37 |
| S44 | 2496   | interconnect\$4 and ((silver or copper or aluminum or gold) near2 sputter\$4)                    | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:38 |
| S45 | 109    | interconnect\$4 and (silver near2 sputter\$4)  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:46 |
| S46 | 0      | interconnect\$4 and (interface near2 silver near2 sputter\$4)                                    | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:39 |
| S47 | 6      | interconnect\$4 and (interface with (silver near2 sputter\$4))                                   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:39 |
| S48 | 2231   | interconnect\$4 and (((titanium with titanium nitride) or (ti with TiN)) near2 sputter\$4)       | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:49 |
| S49 | 513    | interconnect\$4 and (((titanium with (titanium adj nitride)) or (ti with TiN)) near2 sputter\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:53 |
| S50 | 818904 | interconnect\$4  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:53 |
| S51 | 513    | S50 and (((titanium with (titanium adj nitride)) or (ti with TiN)) near2 sputter\$4)             | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 10:55 |
| S52 | 410    | S50 and (titanium near2 sputter\$4) and ((titanium adj nitride) near2 sputter\$4)                | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:00 |

|     |         |  |   |      |     |                  |
|-----|---------|--|---|------|-----|------------------|
| S53 | 0       | S50 and (titanium near2 sputter\$4) and ((titanium adj nitride) near2 sputter\$4) and (silver near sputter\$4)                                 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | ON  | 2005/03/23 11:01 |
| S54 | 67      | S50 and (titanium near2 sputter\$4) and ((titanium adj nitride) near2 sputter\$4) and ((gold or aluminum or copper or silver) near sputter\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | ON  | 2005/03/23 11:11 |
| S55 | 2       | ("5391517").PN.  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | OFF | 2005/03/23 11:53 |
| S56 | 2       | ("6333260").PN.  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | OFF | 2005/07/20 12:46 |
| S57 | 4       | (("6333260") or ("5391517")).PN.   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | OFF | 2005/07/20 12:57 |
| S58 | 7389    | 438/643,597,725,699,644,648,<br>650,658,661,687.ccls.<br><i>686, 660, 637</i>  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR   | ON  | 2005/07/20 12:58 |
| S59 | 4       | S58 and (silver protect\$4 diffus\$4)  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH | ON  | 2005/07/20 13:02 |
| S60 | 1       | S58 and (silver protect\$4 diffus\$4) and (protect\$4 (Ti or TiN or W))  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH | ON  | 2005/07/20 13:10 |
| S61 | 1540465 | semiconductor  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH | ON  | 2005/07/20 14:31 |
| S62 | 13      | S61 and (silver protect\$4 diffus\$4) and (protect\$4 (Ti or TiN or W))  | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | WITH | ON  | 2005/07/20 14:28 |